

SOT1042

polymer strap package; 2 leads; 14 mm wide tape

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	FCS2
Package type industry code	FCS2
Package style descriptive code	FCS (flip chip strap)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-4-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.7	-	14	14.3	mm
E	package width		[tbd]	-	4	[tbd]	mm
A	seated height		[tbd]	-	[tbd]	0.25	mm
A ₂	package height		[tbd]	-	0.02	[tbd]	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

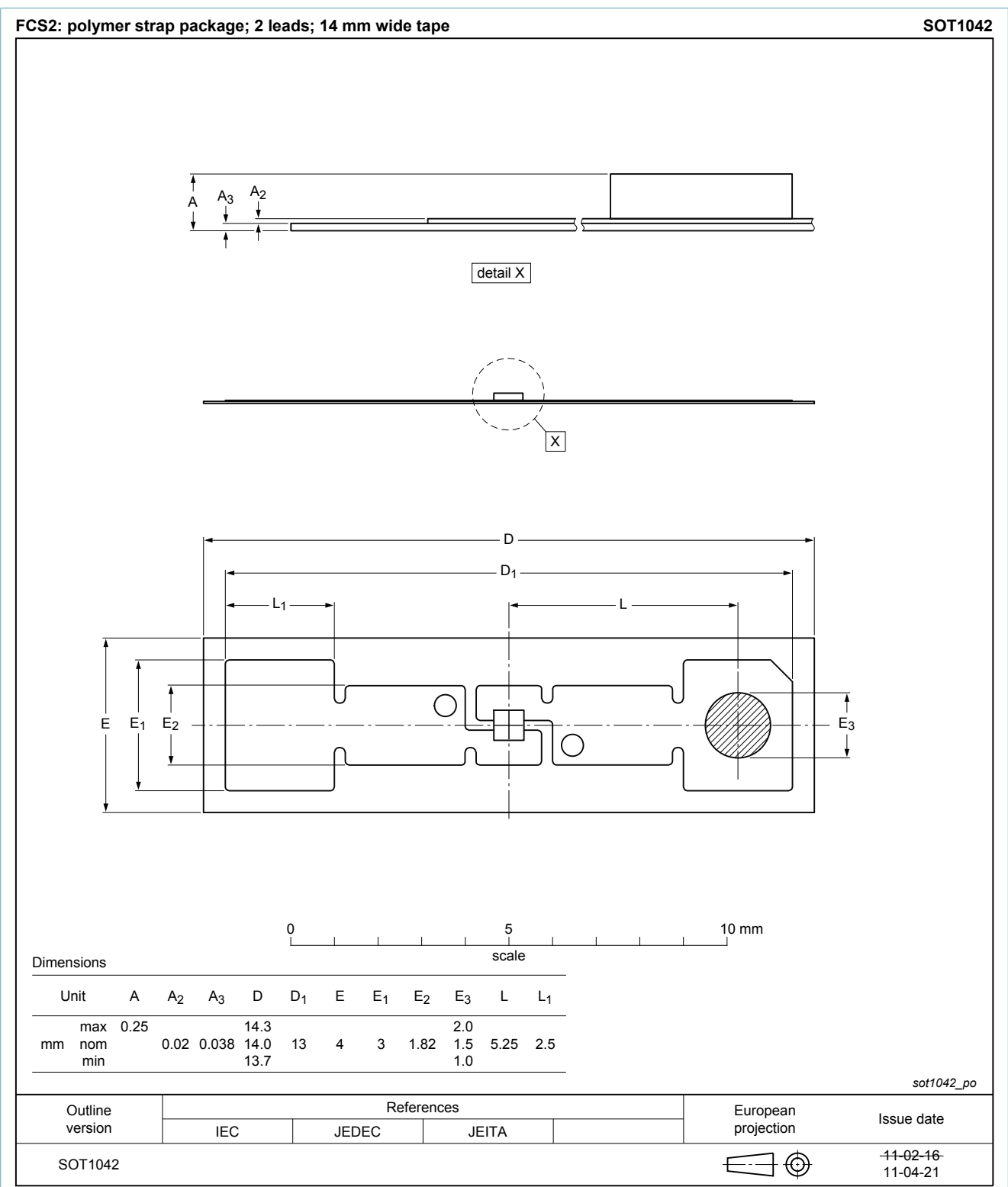


Fig. 1. Package outline FCS2 (SOT1042)

3. Legal information

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